



## PRODUCT DATASHEET



- ▶ PTH/THT Lamp
- ▶ 5mm Round 8.7t

 Phototransistor (PT) for matching N0F00L30

## NOPO8L59 (Bulk) NOPO8L59T (Tape)





## **APPLICATIONS:**

- Remote Control
- Automatic Control System
- Burglar Alarm
- Photo Detector
- Smoke
- Detector
- Computer I/O Peripheral
- Industrial Use

# 5mm Round Lamp Compliant

## **FEATURES:**

N0P08L59 consist of NPN silicon phototransistor mounted in clear lens, is mechanically and spectrally matched to infrared emitting diode N0F00L30 or similar.

- Package: PTH/THT LED Lamp 5mm Round 8.7t
- Wavelength of Max. Sensitivity (typ.): 950nm
- Receiving Angle: 38°
- Materials:
  - Die: Silicon
  - Resin: Epoxy (Black Clear)
- **Operating Temperature:** -40~+85°C
- Storage Temperature: -50~+100°C
- Soldering methods: Hand; Soldering Heat (DIP)
- MSL Level: acc. to JEDEC Level 3
- Packing: 500pcs/bulk; 2000pcs/tape (Ammo Pack)

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## **CHARACTERISTICS:**

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	5	V
Collector-Emitter Sustaining Voltage	V <sub>CE</sub>	30	V
Power Dissipation	PD	100	mW
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	Т <sub>ѕтб</sub>	-50~+100	°C
Relative Humidity at 85°C	hr	85	%

### Electrical & Optical Characteristics (Ta=25°C)

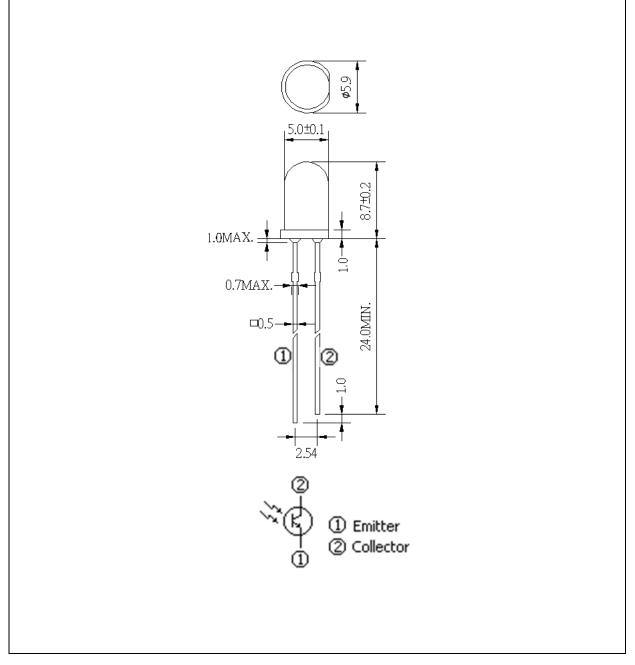
Darameter	Symbol	Values			Linit	Test Candition
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Collector-Emitter Sustaining Voltage	Vce	30	60		V	l <sub>c</sub> =0.5mA Ee=0mW/cm <sup>2</sup>
Collector-Emitter Saturation Voltage	Vce(sat)		0.4		V	I <sub>c</sub> =100μA Ee=0.6mW/cm <sup>2</sup>
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	5	7		V	l <sub>e</sub> =100μA Ee=0mW/cm <sup>2</sup>
Dark Current	lD			100	nA	V <sub>CE</sub> =10V Ee=0mW/cm <sup>2</sup>
Photo Current	ΙL	0.7	4		mA	V <sub>CE</sub> =5V Ee=1.0mW/cm <sup>2</sup>
Rise Time (10% to 90%)	T <sub>R</sub>		10		μS	V <sub>cc</sub> =5V Ι <sub>L</sub> =800μΑ RL=1K OHM
Fall Time (90% to 10%)	T <sub>F</sub>		15		μS	

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## **OUTLINE DIMENSION:**

#### Package Dimension:



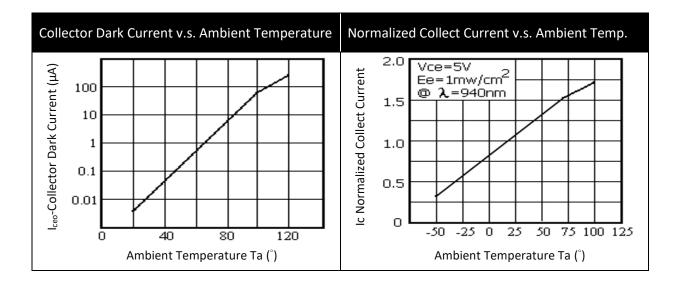
1. All dimensions are in millimetre (mm).

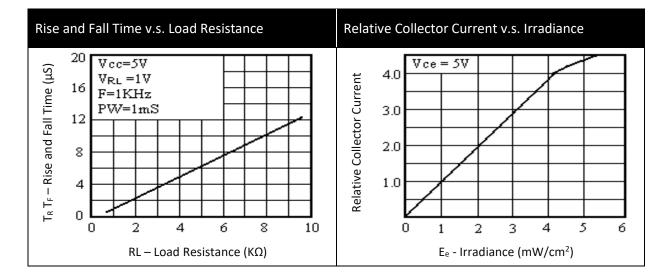
3

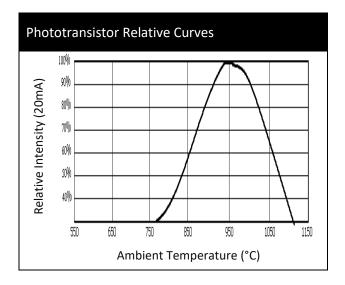
2. Tolerance ±0.2mm, unless otherwise noted.



## **ELECTRO-OPTICAL CHARACTERISTICS:**







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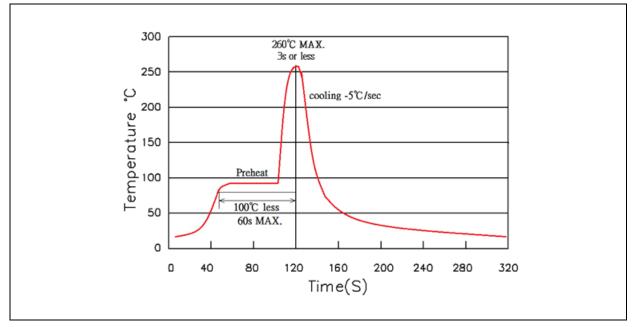


## **RECOMMENDED SOLDERING PROFILE:**

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

#### Soldering Heat (DIP):



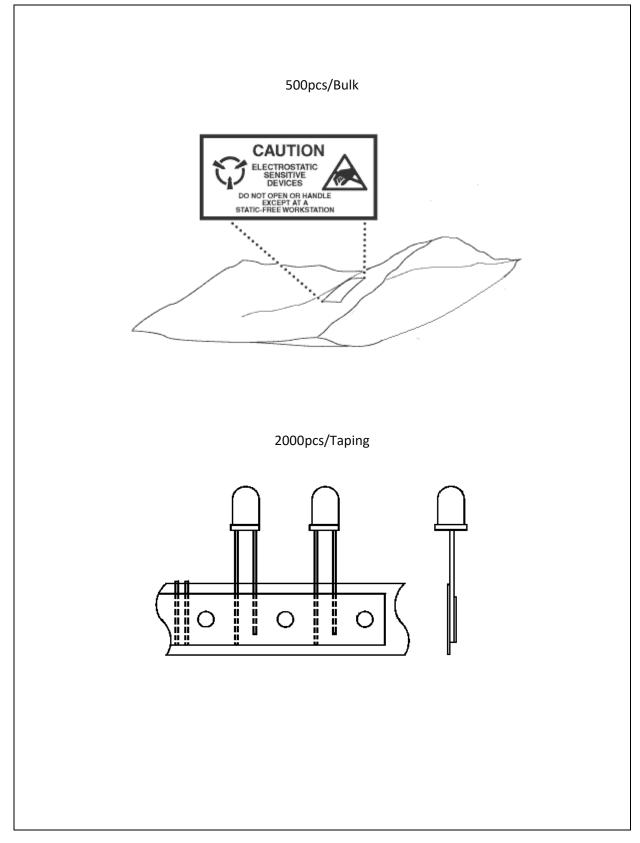
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



## **PACKING SPECIFICATION:**

#### Reel Dimension:



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## **PRECAUTIONS OF USE:**



#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



## **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	16/04/2023	Datasheet set-up.